

Appl. Serial No. 09/681,304
Amdt. Dated March 26, 2004
Reply to Office action of January 12, 2004

Docket No. RD-28435-2

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A method for packaging a microelectromechanical system (MEMS) device comprising:
 - using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;
 - providing a cavity having a smooth surface perimeter and extending through the release sheet and at least partially through the MEMS package flexible layer;
 - removing the release sheet, wherein said providing the cavity comprises, prior to removing the release sheet, providing a hermetic coating in the cavity; and
 - attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity.
2. (Currently amended) The method of claim 1 further comprising providing MEMS vias through the MEMS package flexible layer and [the] a cover extending to connection pads of the MEMS device and applying a MEMS pattern of electrical conductors over the MEMS package flexible layer and the cover and extending through the MEMS vias to the connection pads.
3. (Original) The method of claim 1 wherein using the adhesive to attach the release sheet to the MEMS package flexible comprises coating the MEMS package flexible layer with the adhesive, partially curing the adhesive, and then attaching the release sheet.
4. (Previously amended) The method of claim 3 wherein attaching the MEMS device comprises using the adhesive.

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5. Previously canceled.
6. (Previously amended) The method of claim 1, wherein the adhesive comprises a mixture of photodielectric and epoxy materials.
7. (Currently amended) A method for packaging a microelectromechanical system (MEMS) device comprising:
 - using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;
 - providing a cavity extending through the release sheet and partially through the MEMS package flexible layer;
 - providing a protective coating in the cavity;
 - then removing the release sheet, wherein said providing a protective coating comprises, prior to removing the release sheet, providing a hermetic coating in the cavity;
 - and
 - attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity.
8. Currently canceled.
9. Previously canceled.
10. Previously canceled.
11. Previously canceled.
12. Previously canceled.
13. Previously canceled.

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14. Previously canceled.
15. Previously canceled.
16. Currently canceled.
17. Previously canceled.
18. Previously canceled.
19. (Currently amended) [The method of claim 16] A method for packaging a microelectromechanical system (MEMS) device comprising:
coating a MEMS package flexible layer with an adhesive;
partially curing the adhesive;
using the adhesive to attach a release sheet to the MEMS package flexible layer;
providing a cavity having a smooth surface perimeter and extending through the release sheet, the adhesive, and at least partially through the MEMS package flexible layer;
removing the release sheet, wherein providing the cavity comprises [providing a cavity extending partially through the MEMS package flexible layer and further comprising], prior to removing the release sheet, providing a hermetic coating in the cavity;
using the adhesive to attach the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity;
providing MEMS vias through the MEMS package flexible layer extending to connection pads of the MEMS device; and
applying a MEMS pattern of electrical conductors on the MEMS package flexible layer and extending through the MEMS vias to the connection pads.